



## ZPMV2.E320829 Wiring, Printed - Component

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### Wiring, Printed - Component

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#### MULTECH PCB TECHNOLOGIES CO LTD

E320829

Unit C, 9th Fl  
Winning House  
72-74 Wing Lok St  
Sheung Wan, HONG KONG

Type	Cond Width		Cond	SS/ DS/ DSO	Max Area Diam	Solder		Max Oper Temp	Flame Class	Meets UL796 DSR	C T I
	Min	Edge				Thk	Thk				
Type	mm(in)	mm(in)	mic(mil)	DSO	mm(in)	C	sec	C	Class	DSR	I
<b>Flexible printed wiring boards, flammability only Recognition.</b>											
MUL-RF	-	-	-	DS	-	260	20	-	V-0	-	-
<b>Mass laminated (multilayered) printed wiring boards.</b>											
MUL-SC3	0.075 (0.003)	0.15 (0.006)	17 (0.67)	DS	50.8 (2.0)	260	10	130	V-0	All	-
MULM	0.13 (0.005)	0.18 (0.007)	17 (0.67)	DS	25.4 (1.0)	260	10	130	V-0	All	-
<b>Metal base single-layer printed wiring boards.</b>											
MUL-TT1	0.12 (0.005)	0.12 (0.005)	35 (1.38)	SS	76.0 (3.0)	260	20	130	V-0	-	-
<b>Metal-based single-sided printed wiring boards.</b>											
MUL-K10	0.08 (0.003)	0.24 (0.009)	34 (1.34)	SS	76.2 (3.0)	290	20	110	V-0	All	0
MUL-K11	0.20 (0.008)	0.20 (0.008)	27 (1.06)	SS	76.2 (3.0)	300	16	105	V-0	-	0
MUL-K12	0.29 (0.011)	0.30 (0.012)	140 (5.51)	SS	76.2 (3.0)	288	60	150	V-0	-	0
MUL-K14	0.25 (0.010)	0.27 (0.011)	34 (1.34)	SS	50.8 (2.0)	288	10	90	V-0	All	-
MUL-K15	0.25 (0.010)	0.25 (0.010)	17 (0.67)	SS	50.8 (2.0)	288	60	90	V-0	All	0
MUL-K9	0.20 (0.008)	0.27 (0.011)	35 (1.38)	SS	76.2 (3.0)	288	20	120	V-0	-	0
<b>Multi-layer printed wiring boards.</b>											
MUL-23	0.18 (0.007)	0.53 (0.021)	17 (0.67)	DS	25.4 (1.0)	270	10	130	V-0	All	*
MUL-24	0.09 (0.004)	0.26 (0.010)	17 (0.67) Int:58	DS	76.2 (3.0)	288	20	130	V-0	All	*

<b>MUL-25</b>	0.10 (0.004)	0.26 (0.010)	17 (0.67) Int:204	DS	76.2 (3.0)	288	20	130	V-0	All	*
<b>Multilayer metal-based printed wiring boards.</b>											
<b>MUL-K13</b>	0.20 (0.008)	0.60 (0.024)	17 (0.67) Int:102	SS	76.2 (3.0)	288	60	110	V-0	All	0
<b>Multilayer printed wiring boards.</b>											
<b>MUL-11</b>	0.05 (0.002)	0.12 (0.005)	17 (0.67) Int:34	DS	76.2 (3.0)	260	10	130	V-0	All	-
<b>MUL-12</b>	0.114 (0.004)	0.114 (0.004)	17 (0.67) Int:70	DS	50.8 (2.0)	260	20	100	V-1	-	-
<b>MUL-13</b>	0.125 (0.005)	0.375 (0.015)	17 (0.67) Int:70	DS	50.8 (2.0)	260	20	105	V-0	-	-
<b>MUL-14</b>	1.60 (0.063)	4.80 (0.189)	17 (0.67) Int:70	DS	50.8 (2.0)	260	20	105	V-0	-	-
<b>MUL-15</b>	1.60 (0.063)	4.80 (0.189)	17 (0.67) Int:70	DS	50.8 (2.0)	260	20	105	V-0	-	-
<b>MUL-16(*)</b>	0.08 (0.003)	0.10 (0.004)	17 (0.67) Int:136	DS	25.4 (1.0)	260	10	130	V-0	All	-
<b>MUL-17</b>	0.08 (0.003)	0.12 (0.005)	17 (0.67) Int:34	DS	25.4 (1.0)	260	10	130	V-0	All	-
<b>MUL-18(#)</b>	0.08 (0.003)	0.24 (0.009)	17 (0.67) Int:136	DS	25.4 (1.0)	260	10	130	V-0	All	-
<b>MUL-19</b>	0.08 (0.003)	0.24 (0.009)	17 (0.67) Int:136	DS	25.4 (1.0)	260	10	130	V-0	All	*
<b>MUL-1M</b>	0.07 (0.003)	0.21 (0.008)	12 (0.47) Int:60	DS	76.2 (3.0)	265	5	130	V-0	▲	*
<b>MUL-20</b>	0.08 (0.003)	0.12 (0.005)	17 (0.67) Int:34	DS	76.2 (3.0)	260	10	130	V-0	All	-
<b>MUL-21</b>	0.05 (0.002)	0.12 (0.005)	17 (0.67)	DS	12.7 (0.5)	260	10	130	V-0	All	-
<b>MUL-3M</b>	0.1 (0.004)	0.3 (0.012)	18 (0.71) Int:68	DS	20 (0.8)	288	30	130	V-0	All	-
<b>MUL-4M</b>	0.076 (0.003)	0.23 (0.009)	12 (0.47) Int:102	DS	76.2 (3.0)	288	30	130	V-0	All	-
<b>MUL-K6</b>	0.05 (0.002)	0.15 (0.006)	17 (0.67) Int:102	DS	25.4 (1.0)	288	20	130	V-0	All	*
<b>MUL-K7</b>	0.07 (0.003)	0.11 (0.004)	17 (0.67) Int:102	DS	101.6 (4.0)	288	20	50	V-0	All	-
<b>MUL-K8</b>	0.07 (0.003)	0.11 (0.004)	17 (0.67) Int:102	DS	101.6 (4.0)	288	20	130	V-0	All	*
<b>MUL-ST1</b>	0.09 (0.004)	0.17 (0.007)	17 (0.67) Int:34	DS	25.4 (1.0)	260	20	130	V-0	All	*
<b>MUL-ST2</b>	0.10 (0.004)	0.20 (0.008)	17 (0.67) Int:204	DS	76.2 (3.0)	288	20	125	V-0	All	*
<b>MUL-ST3</b>	0.18 (0.007)	0.18 (0.007)	34 (1.34) Int:136	DS	50.8 (2.0)	288	20	130	V-0	All	*
<b>MUL-ST4 (Note 1)</b>											
	0.08 (0.003)	0.24 (0.009)	12 (0.47) Int:204	DS	76.2 (3.0)	288	20	130	V-0	All	*
<b>MUL-ST5</b>	0.08 (0.003)	0.08 (0.003)	12 (0.47) Int:68	DS	76.2 (3.0)	288	20	130	V-0	All	*
<b>MUL-ST6 (Note 2)</b>											
	0.08 (0.003)	0.24 (0.009)	12 (0.47)	DS	76.2 (3.0)	288	20	130	V-0	All	*

			Int:204								
<b>MUL-TT2</b>	0.05 (0.002)	0.12 (0.005)	17 (0.67) Int:102	DS	75.0 (3.0)	260	20	130	V-0	All	-
<b>MUL-TT3</b>	0.12 (0.005)	0.12 (0.005)	17 (0.67) Int:102	DS	75.0 (3.0)	260	20	130	V-0	All	-
<b>Multilayer printed wiring boards, employing HDI (High Density Interconnect) insulations..</b>											
<b>MUL-HM</b>	0.07 (0.003)	0.21 (0.008)	12 (0.47) Int:40	DS	76.2 (3.0)	265	5	120	V-0	All	*
<b>MUL-M</b>	0.07 (0.003)	0.21 (0.008)	12 (0.47) Int:40	DS	76.2 (3.0)	265	5	105	V-0	All	*
<b>Single layer printed wiring boards.</b>											
<b>MUL-22</b>	0.08 (0.003)	0.24 (0.009)	17 (0.67)	DS	50.8 (2.0)	288	10	130	V-0	All	*
<b>MUL-J1</b>	0.09 (0.004)	0.17 (0.007)	17 (0.67)	DS	25.4 (1.0)	260	20	130	V-0	All	*
<b>MUL-K1</b>	0.07 (0.003)	0.20 (0.008)	17 (0.67)	DS	50.8 (2.0)	288	20	130	V-0	All	*
<b>MUL-K2</b>	0.07 (0.003)	0.11 (0.004)	17 (0.67)	DS	101.6 (4.0)	260	20	130	V-0	All	0
<b>MUL-K3</b>	0.07 (0.003)	0.11 (0.004)	17 (0.67)	DS	101.6 (4.0)	260	20	50	V-0	All	3
<b>MUL-K4</b>	0.07 (0.003)	0.11 (0.004)	17 (0.67)	DS	101.6 (4.0)	288	20	50	V-0	All	3
<b>MUL-K5</b>	0.07 (0.003)	0.11 (0.004)	17 (0.67)	DS	101.6 (4.0)	288	20	130	V-0	All	*
<b>MUL-SC1</b>	0.10 (0.004)	0.15 (0.006)	24 (0.94)	SS	50.8 (2.0)	260	10	130	V-0	All	-
<b>MUL-SC2</b>	0.10 (0.004)	0.15 (0.006)	17 (0.67)	DS	50.8 (2.0)	260	10	130	V-0	All	-
<b>MUL-TT4</b>	0.2 (0.008)	0.58 (0.023)	34 (1.34)	DS	50.8 (2.0)	316	7	130	V-0	All	-
<b>MULD</b>	0.13 (0.005)	0.18 (0.007)	17 (0.67)	DS	25.4 (1.0)	260	10	130	V-0	All	-
<b>MULS</b>	0.13 (0.005)	0.18 (0.007)	17 (0.67)	DS	25.4 (1.0)	260	10	130	V-0	All	-

# - when the external Cu thickness is 136 mic, Min. conductor width is 0.31 mm and Min. Edge conductor width is 0.33 mm

(\*) - When the external copper thickness is 136mic, the min. conductor and min. edge conductor width are both 0.23mm


@ - MAD = 25.4 mm for the copper plane area that may be applied with carbon paste

Note 1 - Min. Cond. Width = 0.08 mm/ Edge Cond. Width = 0.24 mm for External Cu Thk = 12~102 mic; Min. Cond. Width = 0.8 mm/ Edge Cond. Width = 2.4 mm for External Cu Thk = 102~204 mic.

Note 2 - Min. Cond. Width = 0.08 mm/ Edge Cond. Width = 0.24 mm for External Cu Thk = 12~102 mic; Min. Cond. Width = 0.8 mm/ Edge Cond. Width = 2.4 mm for External Cu Thk = 102~170 mic.

\* - CTI marking is optional and may be marked on the printed wiring board.



Marking: Company name or trademark  or file number and type designation. May be followed by a suffix to denote factory identification or burning test classification.

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